



Material Content Data Sheet



Sales Product Name	TLE7237SL			Issued	28. August 2013			
MA#	MA000982086							
Package	PG-SSOP-24-5			Weight*	147.52 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.437	5.04	5.04	50415	50415
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		422	
	non noble metal	iron	7439-89-6	1.245	0.84		8442	
wire	non noble metal	copper	7440-50-8	50.568	34.28	35.17	342782	351752
	noble metal	gold	7440-57-5	0.646	0.44	0.44	4381	4381
	encapsulation	organic material	carbon black	1333-86-4	0.166	0.11		1126
plastics	plastics	epoxy resin	-	7.641	5.18		51796	
	inorganic material	silicondioxide	60676-86-0	75.248	51.01	56.30	510073	562995
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11387	11387
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2476	2476
glue	plastics	acrylic resin	-	0.539	0.37		3651	
	noble metal	silver	7440-22-4	1.909	1.29	1.66	12943	16594
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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